

MECHANICAL CASE OUTLINE

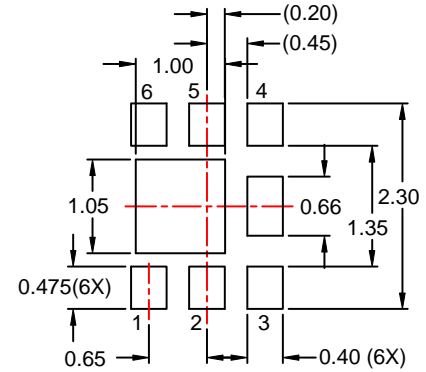
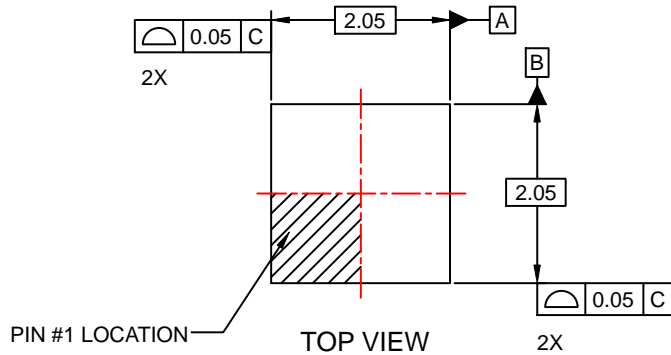
PACKAGE DIMENSIONS

ON Semiconductor®

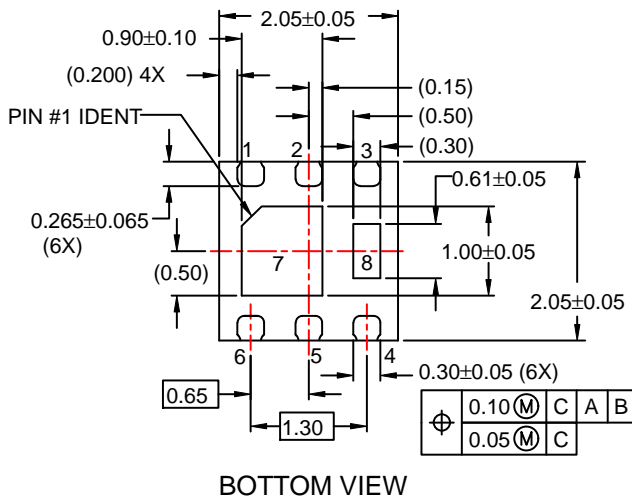
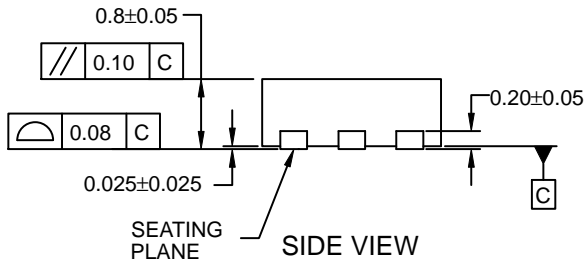


DFN6 2x2, 0.65P
CASE 506DT
ISSUE O

DATE 31 JUL 2016



RECOMMENDED LAND PATTERN



BOTTOM VIEW

Pin #	Function
1	Drain
2	Drain
3	Gate
4	Source
5	Drain
6	Drain
7	Drain
8	Source

NOTES:

- A. PACKAGE DOES NOT CONFORM TO ANY JEDEC STANDARD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DFN6 2X2, 0.65P	PAGE 1 OF 2

